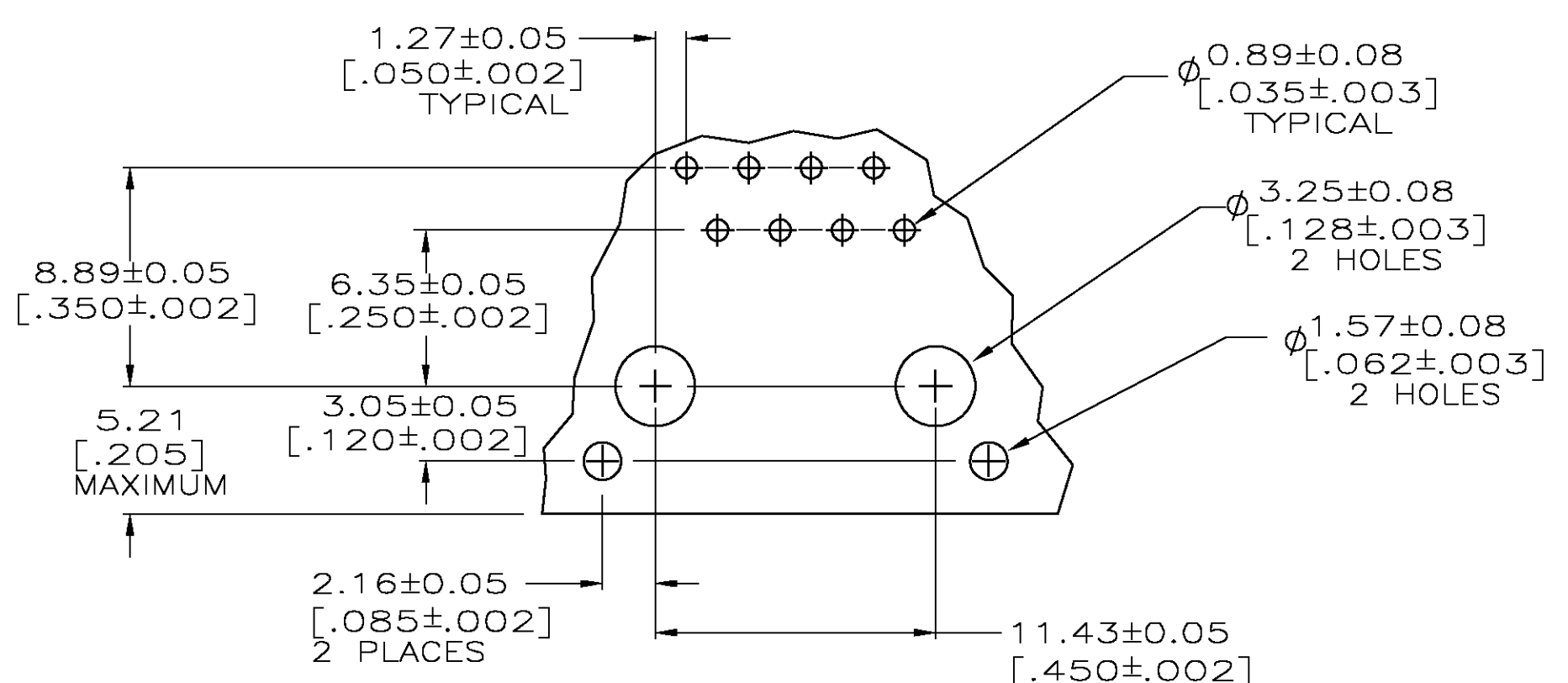
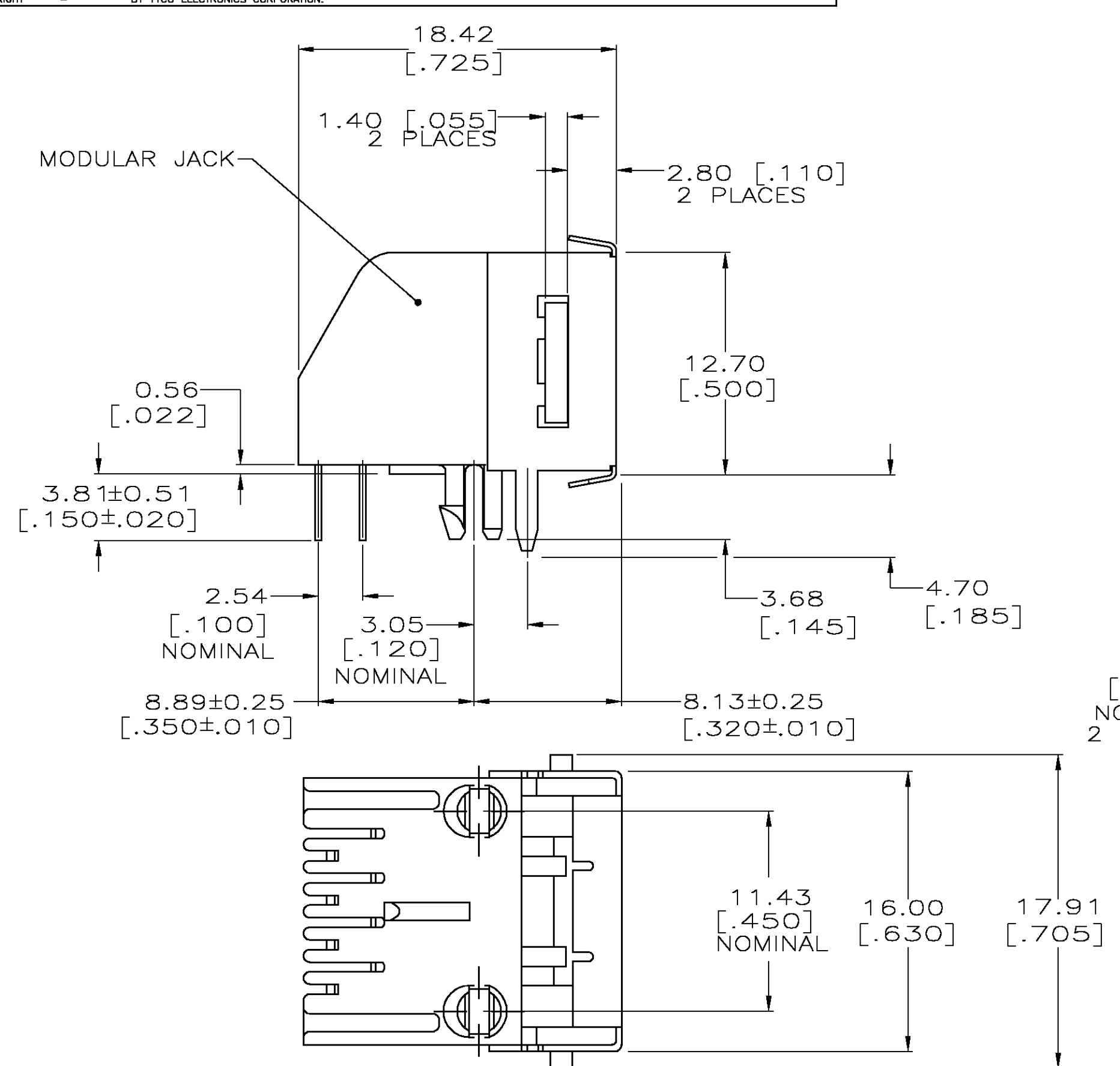


D

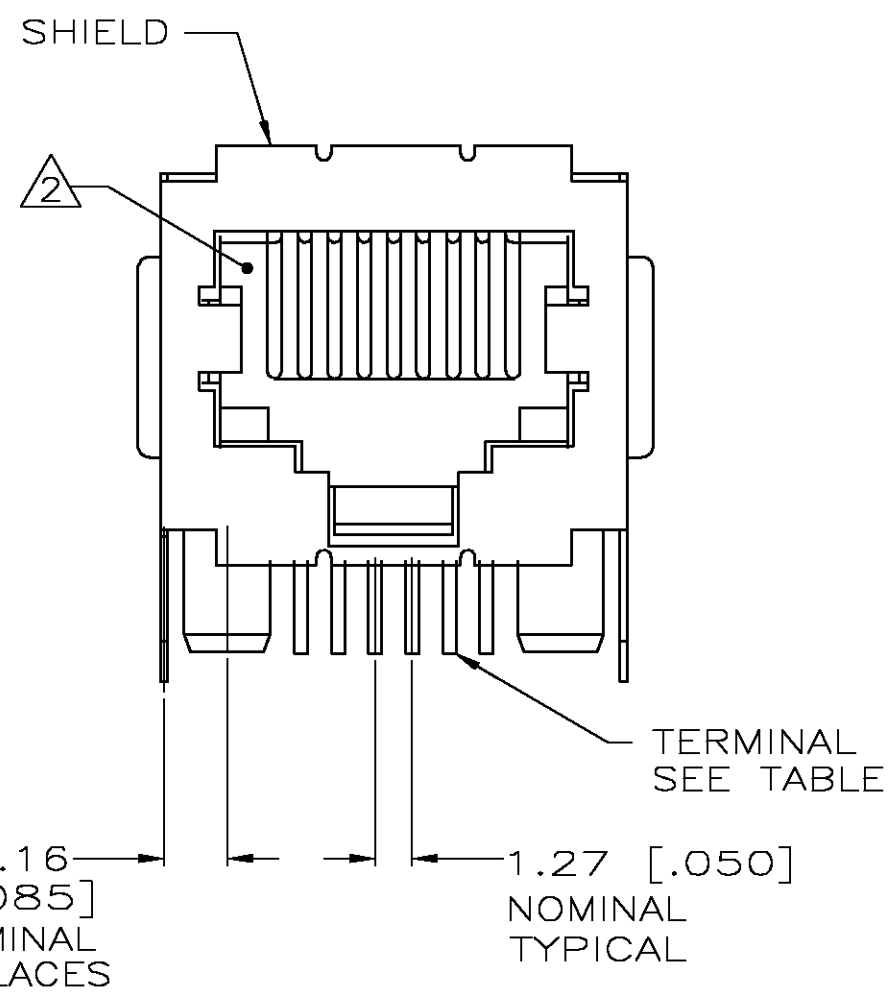
C

B

A



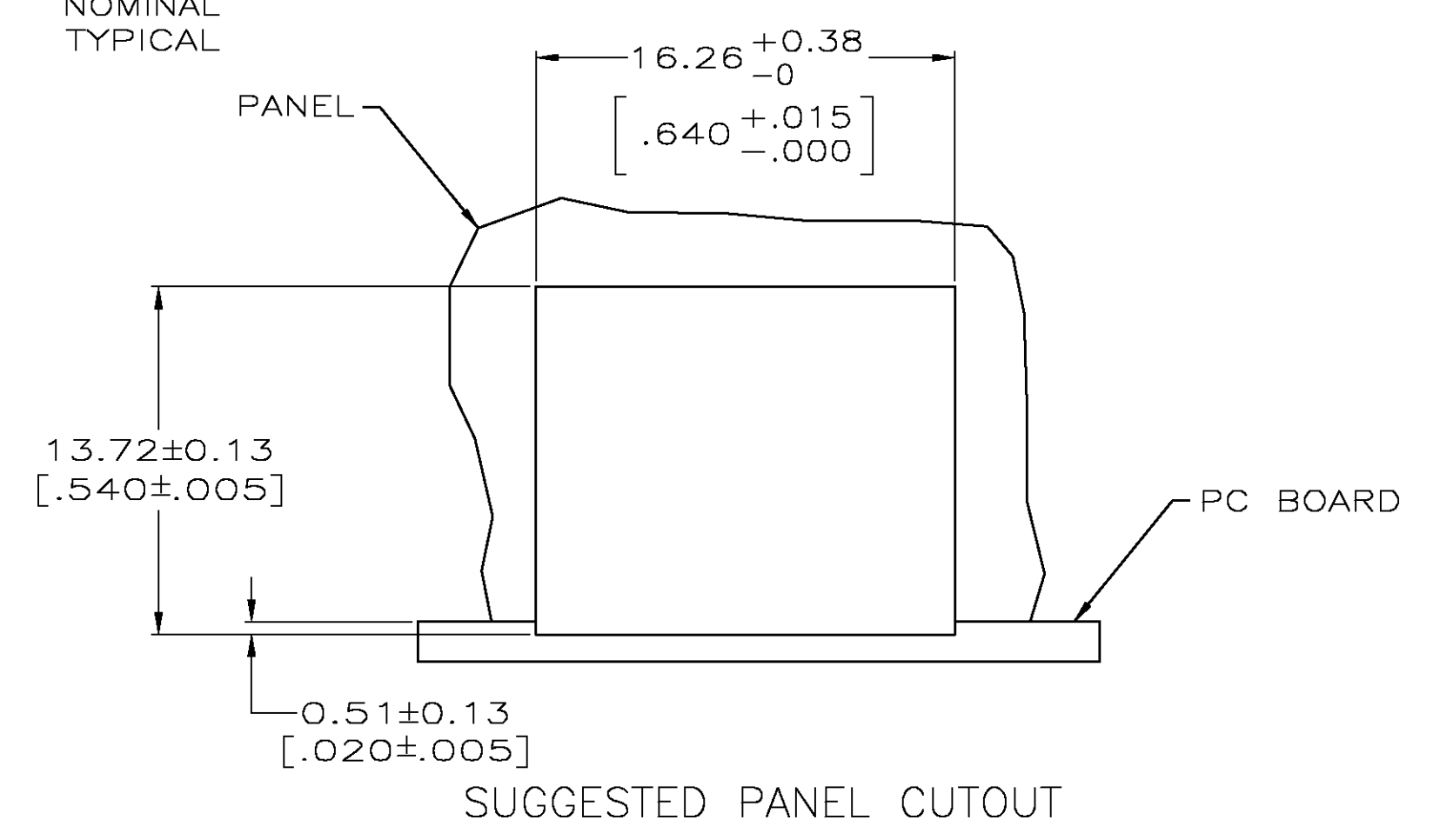
SUGGESTED PRINTED CIRCUIT BOARD
MOUNTING HOLE LAYOUT
VIEW SHOWN AS CIRCUIT SIDE OF BOARD



△ MATERIAL: HOUSING — PER TABLE, BLACK.
TERMINAL — 0.36 [.014] THICK PHOS-BRONZE PLATED
WITH 1.27um [.000050] THICK HARD GOLD IN
LOCALIZED GOLD PLATE AREA AND 3.81um [.000150]
THICK TIN LEAD IN SOLDER AREA OVER
1.27um [.000050] THICK NICKEL UNDERPLATE
SHIELD — 0.25 [.010] THICK COPPER ALLOY,
TIN-LEAD PLATED.

△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS
PART 68, SUBPART F.

3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS
OTHERWISE SPECIFIED.



SUGGESTED PANEL CUTOUT

YES	HIGH TEMP NYLON	555141-3
NO	PBT POLYESTER	555141-1
IR PROCESS COMPATIBLE	HOUSING MATERIAL	PART NUMBER
DWN G. GARRETT 7-10-95	CHK N. JONES 8-25-95	APVD J. TONEY 9-1-95
Tyco Electronics Corporation Harrisburg, PA 17105-3608		
NAME MODULAR JACK ASSEMBLY, SHIELDED, 8 POSITION, LOW PROFILE, RIGHT ANGLE, PANEL GROUND WITH PANEL STOPS		
SIZE A2	CAGE CODE 00779	DRAWING NO 555141
RESTRICTED TO —		
CUSTOMER DRAWING		
SCALE 4:1	SHEET 1 OF 1	REV G